

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT5840712

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIROKI YABUGUCHI	10/17/2019
MISAKI TANIGUCHI	10/17/2019
HIDEKI YOKOYAMA	10/18/2019
RECEIVING PARTY DATA	
Name:	SUMITOMO SEIKA CHEMICALS CO., LTD.
Street Address:	346-1, MIYANISHI
City:	HARIMA-CHO, KAKO-GUN, HYOGO
State/Country:	JAPAN
Postal Code:	675-0145
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16499081
CORRESPONDENCE DATA	
Fax Number:	(612)455-3801
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	612-455-3800
Email:	sfuruya@hsml.com
Correspondent Name:	HAMRE, SCHUMANN, MUELLER & LARSON, P.C.
Address Line 1:	45 SOUTH SEVENTH STREET
Address Line 2:	SUITE 2700
Address Line 4:	MINNEAPOLIS, MINNESOTA 55402-1683
ATTORNEY DOCKET NUMBER:	20539.0030USWO
NAME OF SUBMITTER:	DOUGLAS P. MUELLER
SIGNATURE:	/dpmueller/
DATE SIGNED:	11/26/2019
Total Attachments: 1	
source=Assignment_20539.0030USWO#page1.tif	

ASSIGNMENT

Whereas, I/we,
Name

Address

1) **Hiroki YABUGUCHI**

c/o SUMITOMO SEIKA CHEMICALS CO., LTD.,
 1, Irifune-cho,
 Shikama-ku, Himeji-shi, Hyogo 672-8076 Japan

2) **Misaki TANIGUCHI**

c/o SUMITOMO SEIKA CHEMICALS CO., LTD.,
 1, Irifune-cho,
 Shikama-ku, Himeji-shi, Hyogo 672-8076 Japan

3) **Hideki YOKOYAMA**

c/o SUMITOMO SEIKA CHEMICALS CO., LTD.,
 1, Irifune-cho,
 Shikama-ku, Himeji-shi, Hyogo 672-8076 Japan

hereinafter called assignor(s), have invented certain improvements in

WATER-ABSORBENT RESIN PARTICLES

and executed an application for Letters Patent of the United States of America therefor on even date herewith unless otherwise indicated below:

filed on September 27, 2019, Serial No. 16/499081; and

Whereas

SUMITOMO SEIKA CHEMICALS CO., LTD.

346-1, Miyanishi,

Harima-cho, Kako-gun, Hyogo 675-0145 Japan

(assignee), desires to acquire the entire right, title and interest in the application and invention, and to any United States patents to be obtained therefor;

NOW THEREFORE, be it known that, for good and valuable consideration from assignee, the receipt of which is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

In the event that the patent application filing date or serial number is not known at the time this Assignment is executed, I/WE hereby grant permission to the attorneys of record in the patent application to fill in the filing date and/or serial number above, and to record this Assignment after such information is added.

INVENTORS

DATE SIGNED

1) : Hiroki Yabuguchi
 Name : Hiroki YABUGUCHI

October 17, 2019

2) : Misaki Taniguchi
 Name : Misaki TANIGUCHI

October 17, 2019

3) : Hideki Yokoyama
 Name : Hideki YOKOYAMA

October 18, 2019